

3/a 7-18-01

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

International Application No. PCT/JP00/04199

International Filing Date: June 27, 2000

Title: THROUGH HOLE CONDUCTION STRUCTURE OF FLEXIBLE MULTILAYER

CIRCUIT BOARD AND FORMING METHOD THEREOF

Applicants for US: Kenichi HIRAHARA

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Box PCT Commissioner for Patents Washington, D.C. 20231

Sir:

## PRELIMINARY AMENDMENT

Prior to calculation of the filing fee and examination of the application, please enter the following amendments:

## **AMENDMENT**

In the specification:

Page 1, after the title, insert the following heading and paragraph:

-- Cross-Reference To Related Application

This is the U.S. national phase of International Application No. PCT/JP00/04199

filed June 27, 2000 .--

Page 5, line 46, delete the first occurrence of the word "the".

Page 5, line 21, replace "1" with --11--.

The paragraph spanning lines 16-25 of page 5, after the above amendments should read as follows:

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On both sides of the internal layer flexible circuit board, single-sided copper-clad laminates having the conduction layers 6 and 9 consisting of copper foils and the like are superimposed on the flexible insulating base materials 7 and 10 consisting of polymide films through adhesive layers 8 and 11 of the pre-preg to constitute respective external layer circuit boards each of which can be a mounting portion.

## REMARKS

Applicant has amended the specification to reference the corresponding PCT application.

Page 5 of the specification has been amended to correct minor clerical errors.

Applicant requests that the amendments be entered prior to assessing the filing fee and examining the application.

Respectfully submitted,

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